

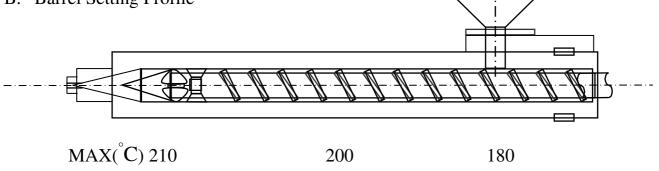
High Clear SAN, KIBISAN[®] PN-106 L150

April 28, 2010

V1W

Processing Conditions :

- A Pre-drying $75 \sim 80^{\circ}$ C x $3 \sim 4$ hrs
 - depending on a) Humidity
 - b) Ratio of reground resin
 - c) Storage conditions
- B. Barrel Setting Profile



$MIN(^{\circ}C)$ 180 180 160

C. Mold Temperature $40 \sim 60^{\circ} C$

	depending on	a) Thickness
		b) Dimension
		c) Gate and runner system
D.	Injection Pressu	re $50 \sim 70 \text{ kg/cm}^2$
	Holding Pressu	$40 \sim 60 \text{ kg/cm}^2$

Back Pressure $5 \sim 15 \text{ kg/cm}^2$

NOTE :

- 1. Keep the resin from dust and contamination during handling and production.
- 2. Do not retain the hot melt at the barrel for a long time between injection cycles.
- 3. Temperature setting of manifold system should not exceed 230° C to avoid melt from degrading.

For further information, please contact your local agent or fax to Chi Mei Technical Services Dept. at 886-6-2665555